

# SEMICONDUCTOR WBM

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## Manual Wetbench for wetchemical processing

This flexible manually operated wetbench system can be used for various applications in semiconductor, microsystem and solar technologies. The modular design allows customised configurations according to your process requirements. The process modules are available in different materials eg. PP, PPs, PVDF, ECTFE, stainless steel or quartz.

### Areas of application

- General wet chemical processing such as cleaning, etching, stripping
- Additional process solutions such as drying, spin processing
- Pre- and post-treatments for plating processes
- Compatible with RENA EPM manual electroplating systems

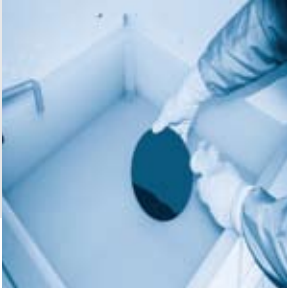
### Features and benefits

- Modular design
- Very small footprint
- Customised solutions for every budget
- Useable for 2" to 12" wafers and special substrate dimensions
- Corresponding plating modules available
- Low budget solution with high reliability
- Various options available: conductivity measurement, flow box, wafer tweezer, Spin Rinse Dryer (SRD) for single wafer or carrier, substrate agitation
- Operator friendly
- Easy maintenance access





Rinsing module



Multifunctional sink



Modular design

## Technical Data WBM

Process	<ul style="list-style-type: none"> <li>• Rinsing, etching, stripping, drying</li> <li>• E.g. SC1, SC2, HF, KOH, H2SO4</li> </ul>
Dimensions	400 x 1.000 x 2.050 mm per module (length x width x height)
Throughput	Depending on process
Wafer thickness	Depending on process
Media consumption	<ul style="list-style-type: none"> <li>• DI water</li> <li>• Electricity</li> <li>• Exhaust</li> <li>• Compressed air for pneumatic</li> </ul>
	<p>depending on configuration</p> <p>380-400V; 50-60Hz, 16-32 A</p> <p>~ 450m<sup>3</sup>/h per module</p>